

SN54LVTH16652, SN74LVTH16652 3.3-V ABT 16-BIT BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCBS150K – JULY 1994 – REVISED APRIL 1999

- Members of the Texas Instruments *Widebus™* Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- I_{off} and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model ($C = 200$ pF, $R = 0$)
- Package Options Include Plastic Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

SN54LVTH16652 . . . WD PACKAGE
SN74LVTH16652 . . . DGG OR DL PACKAGE
(TOP VIEW)

1OEAB	1	56	1OEBA
1CLKAB	2	55	1CLKBA
1SAB	3	54	1SBA
GND	4	53	GND
1A1	5	52	1B1
1A2	6	51	1B2
V_{CC}	7	50	V_{CC}
1A3	8	49	1B3
1A4	9	48	1B4
1A5	10	47	1B5
GND	11	46	GND
1A6	12	45	1B6
1A7	13	44	1B7
1A8	14	43	1B8
2A1	15	42	2B1
2A2	16	41	2B2
2A3	17	40	2B3
GND	18	39	GND
2A4	19	38	2B4
2A5	20	37	2B5
2A6	21	36	2B6
V_{CC}	22	35	V_{CC}
2A7	23	34	2B7
2A8	24	33	2B8
GND	25	32	GND
2SAB	26	31	2SBA
2CLKAB	27	30	2CLKBA
2OEAB	28	29	2OEBA

description

The 'LVTH16652 devices are 16-bit bus transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices can be used as two 8-bit transceivers or one 16-bit transceiver.

Output-enable (OEAB and \overline{OEBA}) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. A low input level selects real-time data, and a high input level selects stored data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'LVTH16652 devices.



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**TEXAS
INSTRUMENTS**

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3.3-V ABT 16-BIT BUS TRANSCEIVERS AND REGISTERS

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description (continued)

Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs, regardless of the levels on the select-control or output-enable inputs. When SAB and SBA are in the real-time transfer mode, it also is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last level configuration.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

The SN54LVTH16652 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74LVTH16652 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

INPUTS						DATA I/O†		OPERATION OR FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	
L	H	H or L	H or L	X	X	Input	Input	Isolation
L	H	↑	↑	X	X	Input	Input	Store A and B data
X	H	↑	H or L	X	X	Input	Unspecified‡	Store A, hold B
H	H	↑	↑	X‡	X	Input	Output	Store A in both registers
L	X	H or L	↑	X	X	Unspecified‡	Input	Hold A, store B
L	L	↑	↑	X	X‡	Output	Input	Store B in both registers
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	H or L	X	H	Output	Input	Stored B data to A bus
H	H	X	X	L	X	Input	Output	Real-time A data to B bus
H	H	H or L	X	H	X	Input	Output	Stored A data to B bus
H	L	H or L	H or L	H	H	Output	Output	Stored A data to B bus and stored B data to A bus

† The data-output functions may be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

‡ Select control = L; clocks can occur simultaneously.

Select control = H; clocks must be staggered to load both registers.

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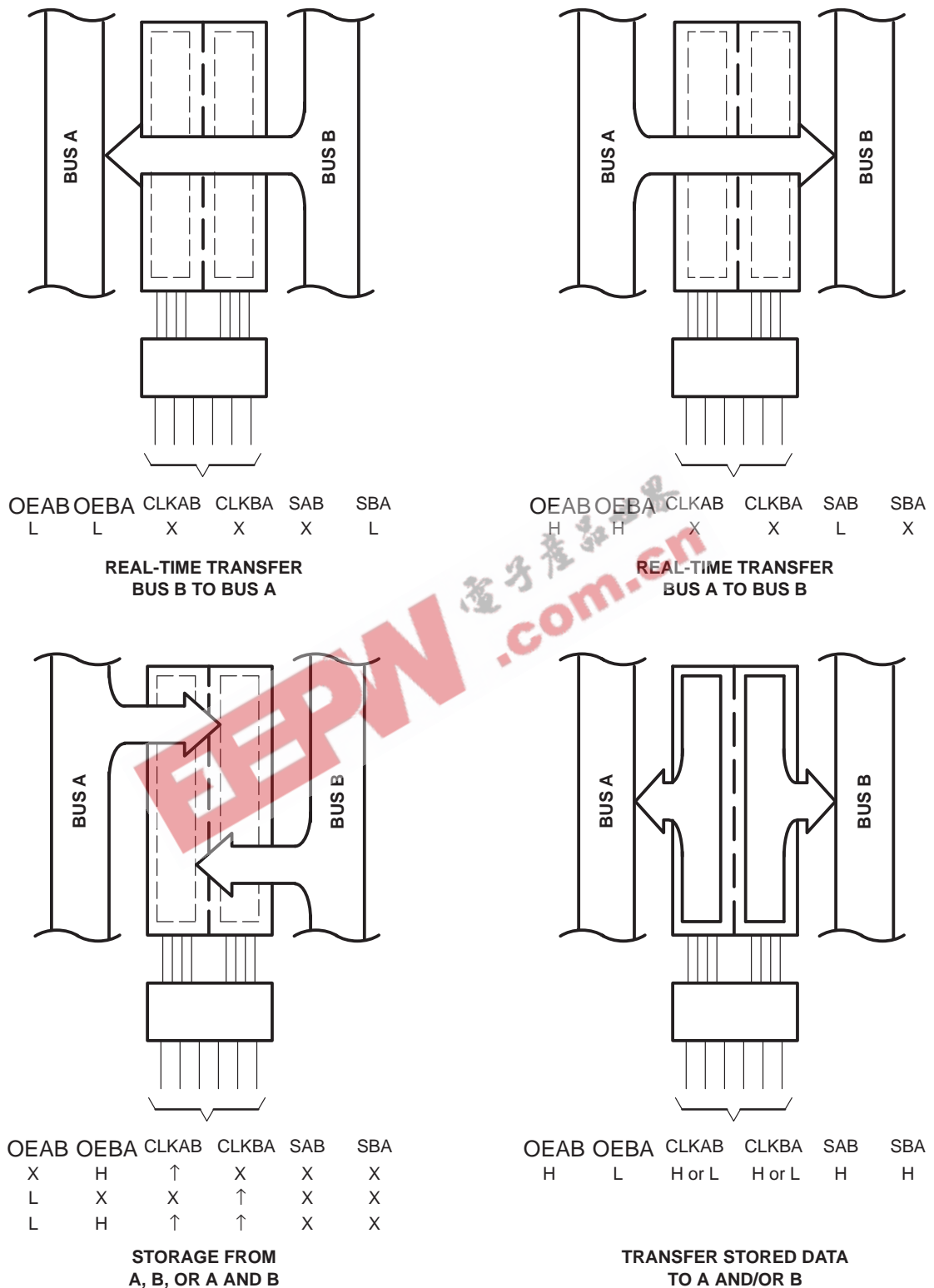


Figure 1. Bus-Management Functions

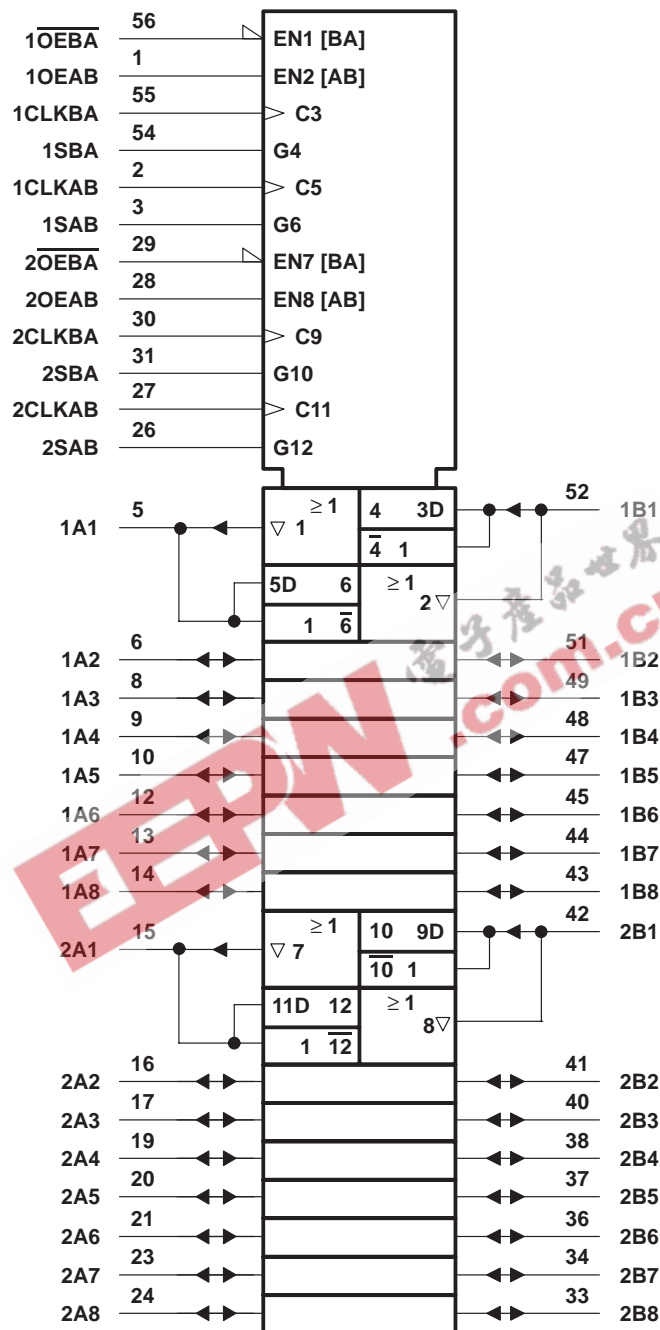
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logic symbol†

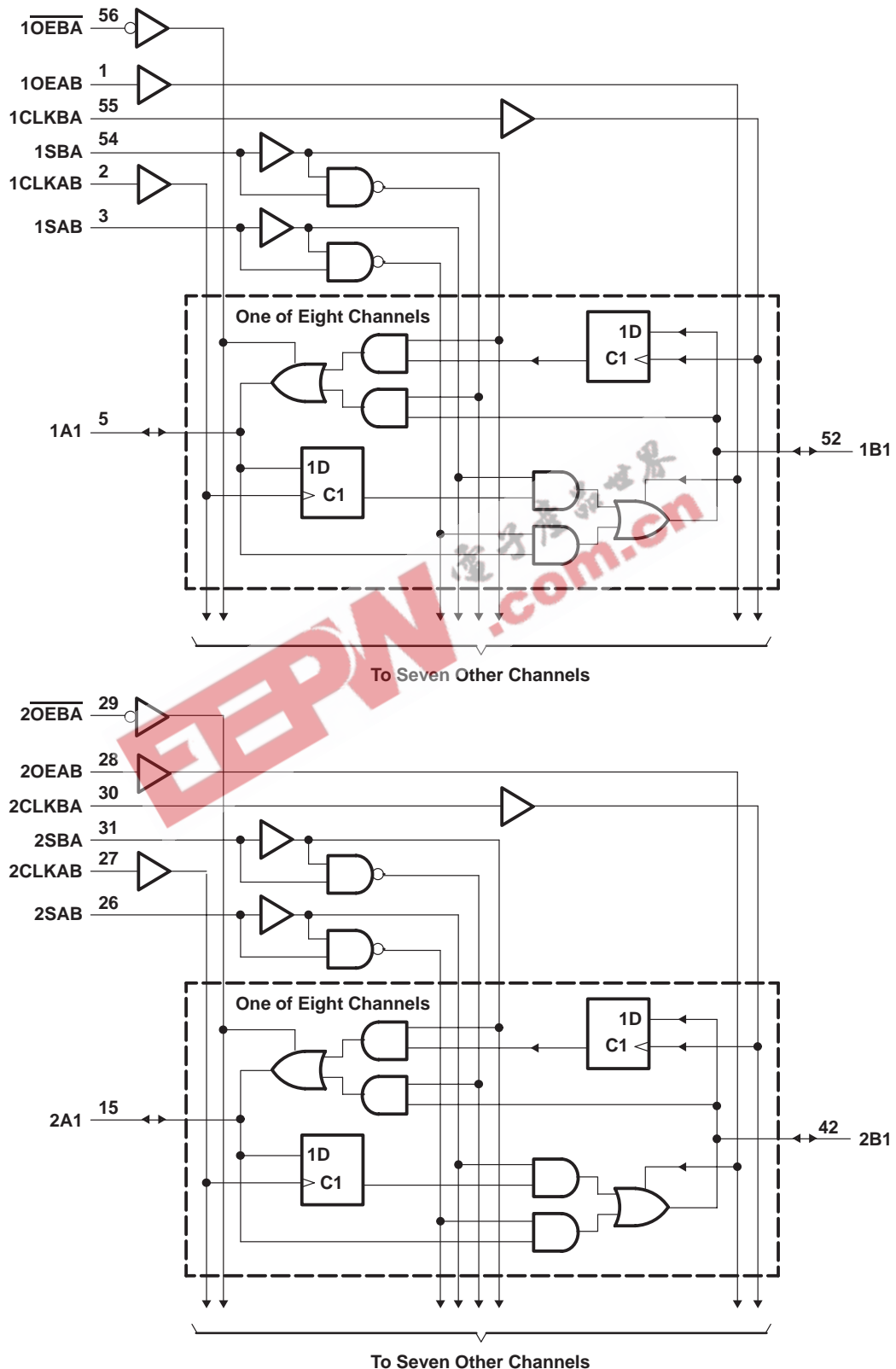


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Current into any output in the low state, I_O : SN54LVTH16652	96 mA
SN74LVTH16652	128 mA
Current into any output in the high state, I_O (see Note 2): SN54LVTH16652	48 mA
SN74LVTH16652	64 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 3): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
3. The package thermal impedance is calculated in accordance with JEDEC 51.

recommended operating conditions (see Note 4)

			SN54LVTH16652		SN74LVTH16652		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2.7	3.6	2.7	3.6	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage			5.5		5.5	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54LVTH16652			SN74LVTH16652			UNIT	
				MIN	TYP†	MAX	MIN	TYP†	MAX		
V _{IK}		V _{CC} = 2.7 V, I _I = -18 mA		-1.2			-1.2			V	
V _{OH}		V _{CC} = 2.7 V to 3.6 V, I _{OH} = -100 μA		V _{CC} -0.2			V _{CC} -0.2			V	
		V _{CC} = 2.7 V, I _{OH} = -8 mA		2.4			2.4				
		V _{CC} = 3 V, I _{OH} = -24 mA		2							
		I _{OH} = -32 mA					2				
V _{OL}		V _{CC} = 2.7 V, I _{OL} = 100 μA		0.2			0.2			V	
		I _{OL} = 24 mA		0.5			0.5				
		V _{CC} = 3 V, I _{OL} = 16 mA		0.4			0.4				
		I _{OL} = 32 mA		0.5			0.5				
		I _{OL} = 48 mA		0.55							
		I _{OL} = 64 mA					0.55				
I _I	Control inputs	V _{CC} = 0 or 3.6 V, V _I = 5.5 V		10			10			μA	
		V _{CC} = 3.6 V, V _I = V _{CC} or GND		±1			±1				
	A or B ports‡	V _{CC} = 3.6 V, V _I = 5.5 V		20			20				
		V _I = V _{CC}		1			1				
		V _I = 0		-5			-5				
I _{off}		V _{CC} = 0, V _I or V _O = 0 to 4.5 V					±100			μA	
I _I (hold)	A or B ports	V _{CC} = 3 V, V _I = 0.8 V		75			75			μA	
		V _I = 2 V		-75			-75				
		V _{CC} = 3.6 V§, V _I = 0 to 3.6 V					±500				
I _{OZPU}		V _{CC} = 0 to 1.5 V, V _O = 0.5 V to 3 V, OE/OE = don't care		±100*			±100			μA	
I _{OZPD}		V _{CC} = 1.5 V to 0, V _O = 0.5 V to 3 V, OE/OE = don't care		±100*			±100			μA	
I _{CC}		V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND		Outputs high		0.19			0.19		mA
				Outputs low		5			5		
				Outputs disabled		0.19			0.19		
ΔI _{CC} ¶		V _{CC} = 3 V to 3.6 V, One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND		0.2			0.2			mA	
C _i		V _I = 3 V or 0		4			4			pF	
C _{io}		V _O = 3 V or 0		10			10			pF	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ Unused pins at $V_{CC}\text{ or GND}$

§ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than $V_{CC}\text{ or GND}$.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

			SN54LVTH16652				SN74LVTH16652				UNIT
			$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3 \pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency		150		150		150		150		MHz
t _w	Pulse duration, CLK high or low		3.3		3.3		3.3		3.3		ns
t _{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	Data high	1.2		1.5		1.2		1.5		ns
		Data low	2		2.8		2		2.8		
t _h	Hold time, A or B after CLKAB↑ or CLKBA↑	Data high	0.5		0		0.5		0		ns
		Data low	0.5		0.5		0.5		0.5		

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 2)

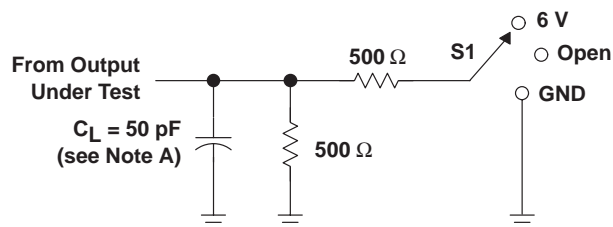
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVTH16652				SN74LVTH16652				UNIT	
			V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN		MAX
f _{max}			150		150		150		150		MHz	
t _{PLH}	CLK	B or A	1.3	4.5	5		1.3	2.7	4.2	4.7		ns
t _{PHL}			1.3	4.5	5		1.3	2.8	4.2	4.7		
t _{PLH}	A or B	B or A	1	3.6	4.1		1	2.4	3.4	3.9		ns
t _{PHL}			1	3.6	4.1		1	2.1	3.4	3.9		
t _{PLH}	SAB or SBA	B or A	1	4.7	5.6		1	2.7	4.5	5.4		ns
t _{PHL}			1	4.7	5.6		1	3	4.5	5.4		
t _{PZH}	$\overline{\text{OEBA}}$	A	1	4.5	5.4		1	2.4	4.3	5.2		ns
t _{PZL}			1	4.5	5.4		1	2.3	4.3	5.2		
t _{PHZ}	$\overline{\text{OEBA}}$	A	2	5.8	6.3		2	3.9	5.6	6.1		ns
t _{PLZ}			2	5.6	6.3		2	3.4	5.4	6.1		
t _{PZH}	OEAB	B	1.3	4.4	5.1		1.3	2.7	4.2	4.9		ns
t _{PZL}			1.3	4.4	5.1		1.3	2.6	4.2	4.9		
t _{PHZ}	OEAB	B	1.6	5.8	6.5		1.3	3.5	5.5	6.2		ns
t _{PLZ}			1.6	5.8	6.5		1.3	3.2	5.5	6.2		

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

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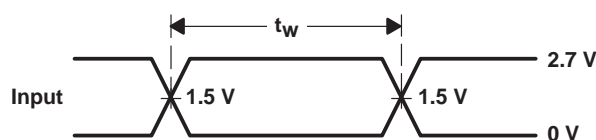
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PARAMETER MEASUREMENT INFORMATION

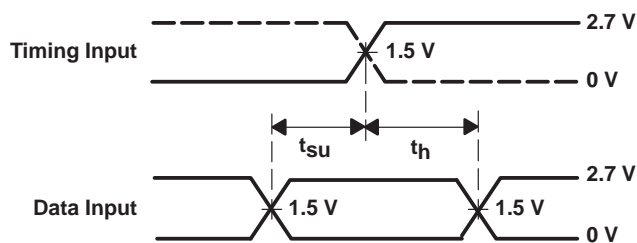


LOAD CIRCUIT

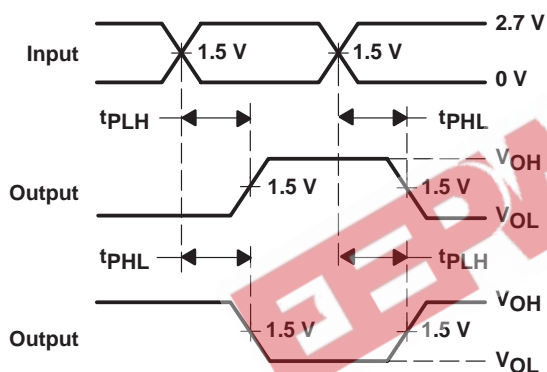
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



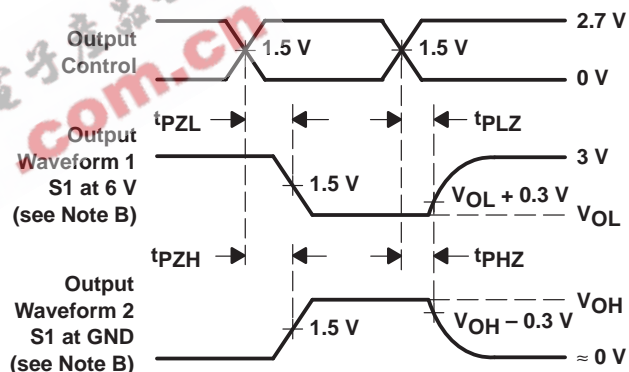
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74LVTH16652DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
74LVTH16652DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH16652DGGR	ACTIVE	TSSOP	DGG	56	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LVTH16652DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH16652DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH16652DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

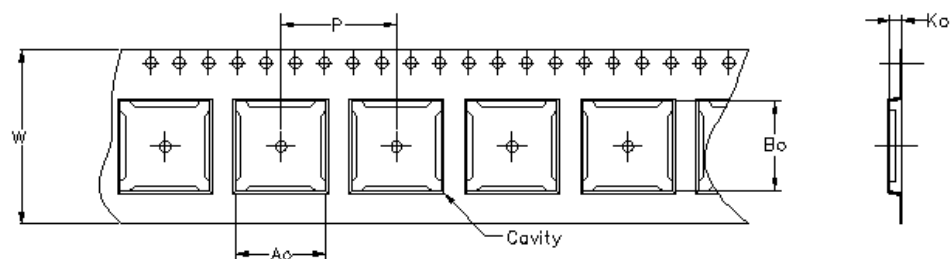
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

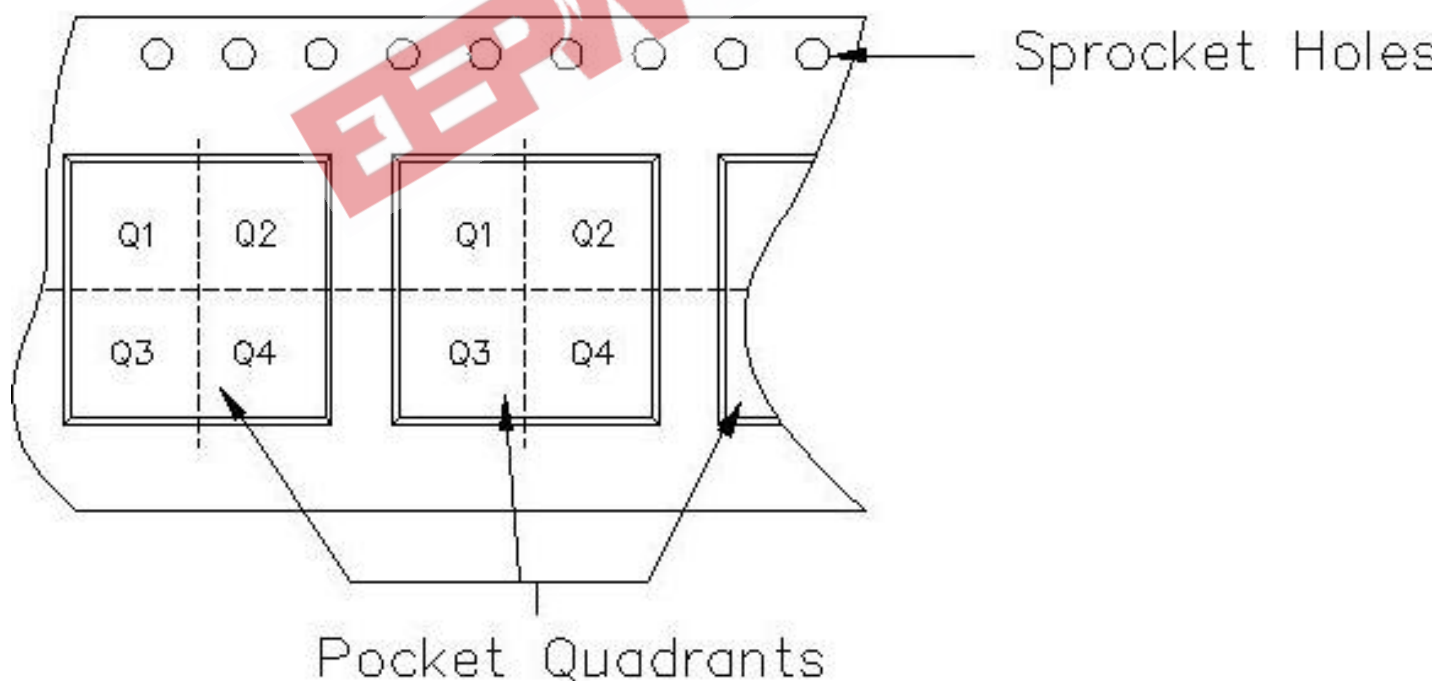
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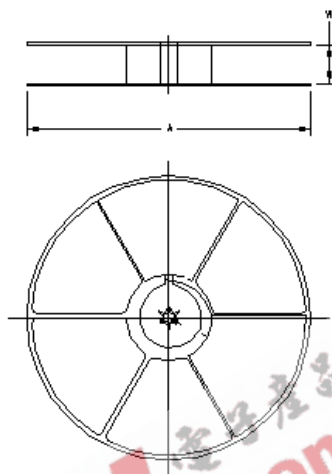
Carrier tape design is defined largely by the component length, width, and thickness.

A_o = Dimension designed to accommodate the component width.
B_o = Dimension designed to accommodate the component length.
K_o = Dimension designed to accommodate the component thickness.
W = Overall width of the carrier tape.
P = Pitch between successive cavity centers.



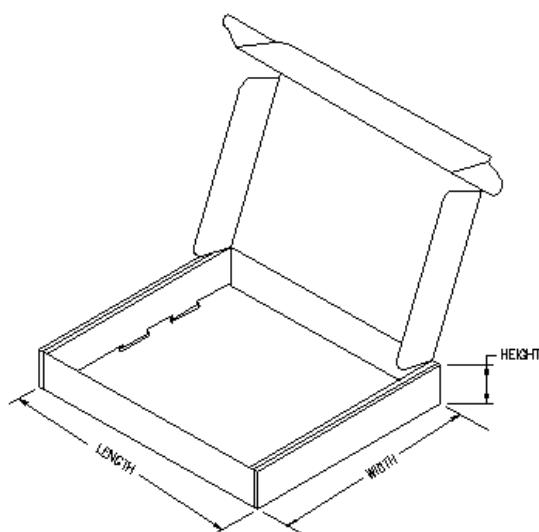
TAPE AND REEL INFORMATION

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH16652DGGR	DGG	56	MLA	330	24	8.6	15.8	1.8	12	24	Q1
SN74LVTH16652DLR	DL	56	MLA	330	32	11.35	18.67	3.1	16	32	Q1



TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74LVTH16652DGGR	DGG	56	MLA	333.2	333.2	31.75
SN74LVTH16652DLR	DL	56	MLA	346.0	346.0	49.0



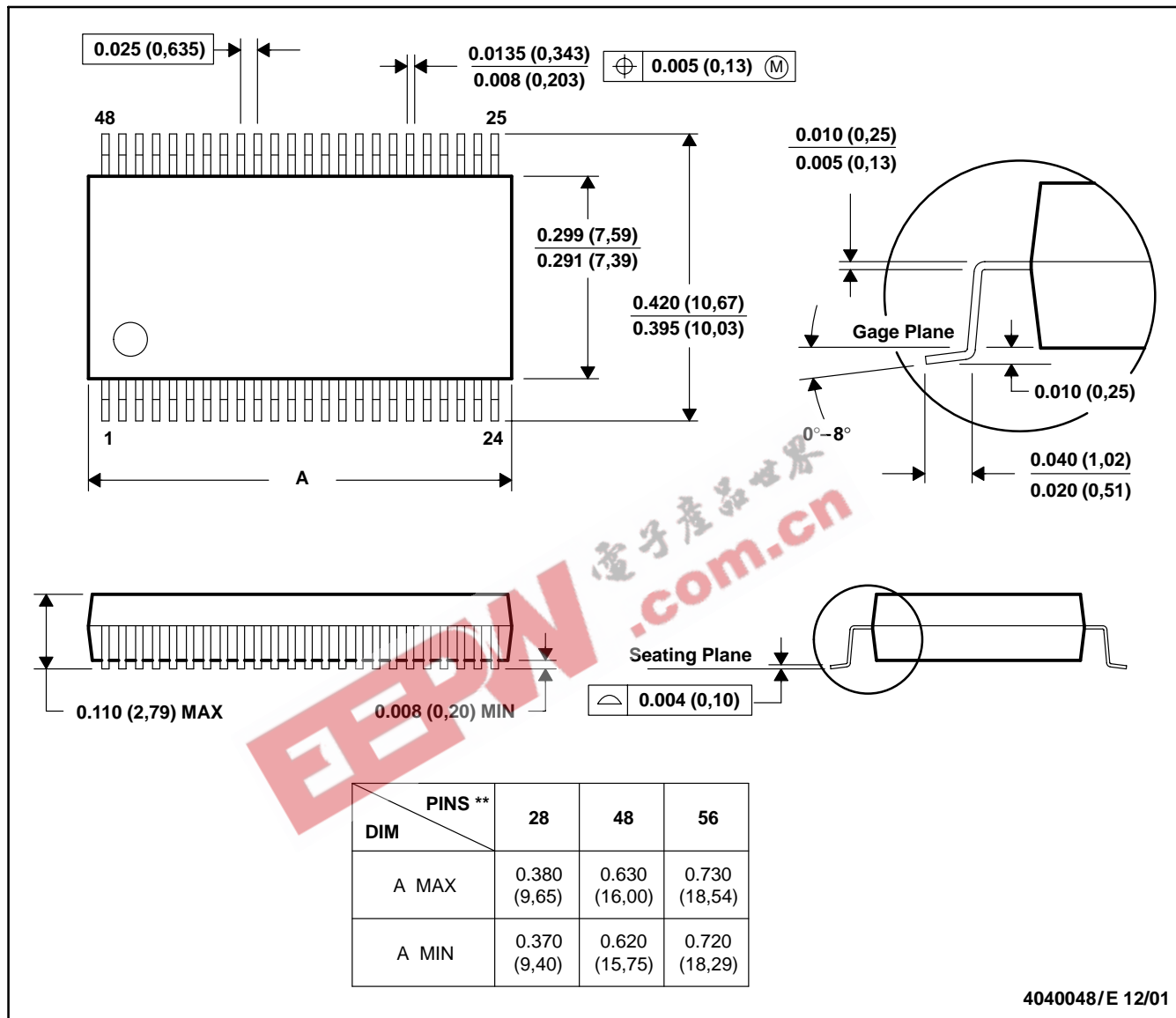
MECHANICAL DATA

MSSO001C – JANUARY 1995 – REVISED DECEMBER 2001

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MO-118

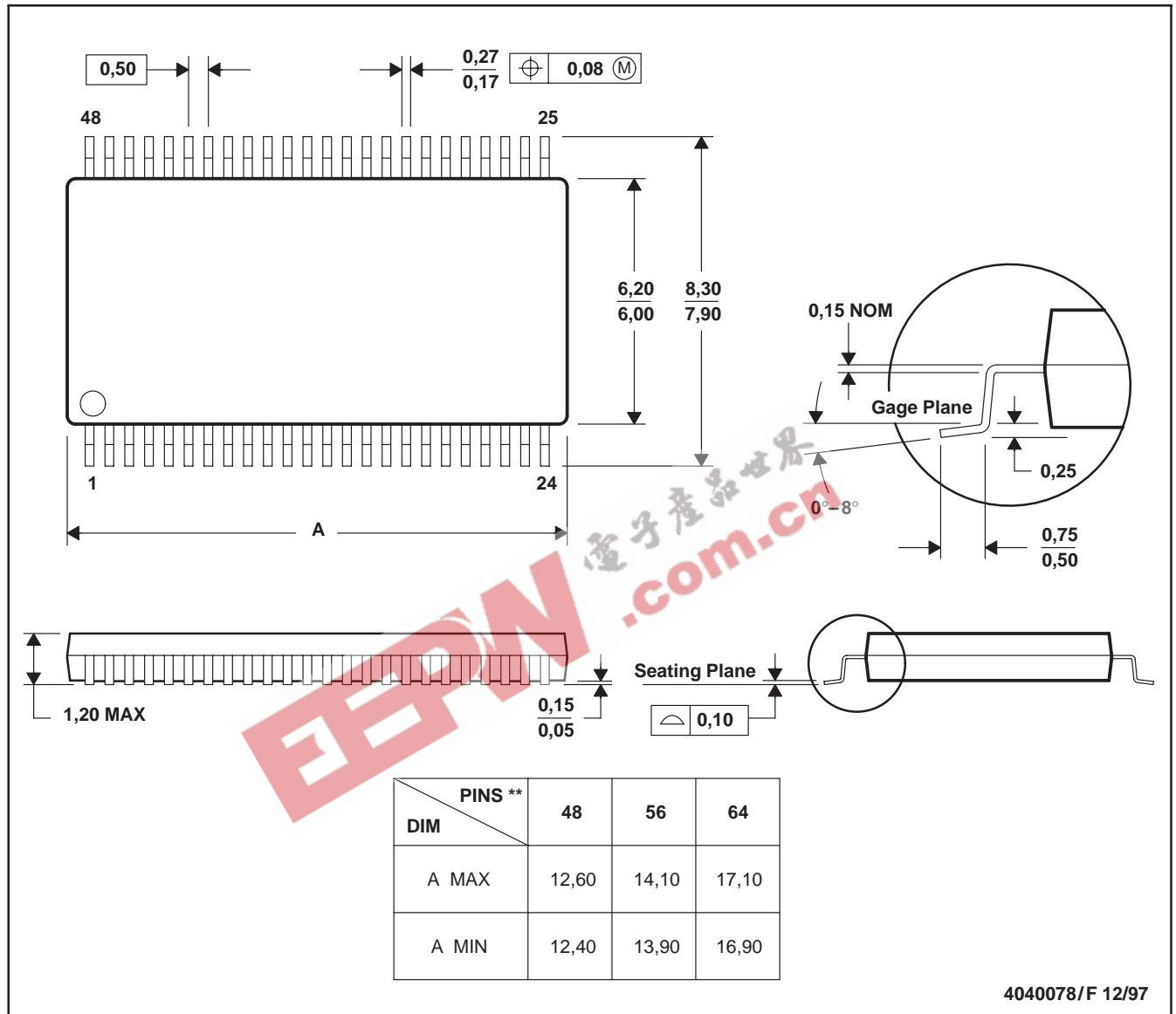
MECHANICAL DATA

MTSS003D – JANUARY 1995 – REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold protrusion not to exceed 0,15.
 - D. Falls within JEDEC MO-153

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